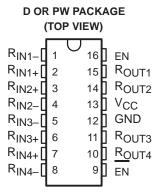
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- >400 Mbps (200 MHz) Signaling Rates
- Flow-Through Pinout Simplifies PCB Layout
- 50 ps Channel-to-Channel Skew (Typ)
- 200 ps Differential Skew (Typ)
- **Propagation Delay Times 2.7 ns (Typ)**
- 3.3 V Power Supply Design
- **High-Impedance LVDS Inputs on Power** Down
- Low-Power Dissipation (40 mW at 3.3 V
- Accepts Small Swing (350 mV) Differential Signal Levels
- Supports Open, Short, and Terminated Input Fail-Safe
- **Industrial Operating Temperature Range** (-40°C to 85°C)
- Conforms to TIA/EIA-644 LVDS Standard
- Available in SOIC and TSSOP Packages
- Pin-Compatible With DS90LV048A From **National**

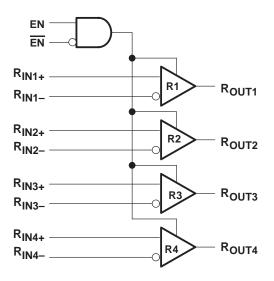
## description

The SN65LVDS048 is a quad differential line receiver that implements the electrical characteristics of low-voltage differential signaling (LVDS). This signaling technique lowers the output voltage levels of 5-V differential standard levels (such as EIA/TIA-422B) to reduce the power, increase the switching speeds, and allow operation with a 3.3-V supply rail. Any of the guad differential receivers will provide a valid logical output state with a ±100-mV differential input voltage within the input common-mode voltage range. The input common-mode voltage range allows 1 V of ground potential difference between two LVDS nodes.

## NOT RECOMMENDED FOR NEW DESIGNS For Replacement Use SN65LVDS048A



## functional diagram



The intended application of this device and signaling technique is for point-to-point baseband data transmission over controlled impedance media of approximately 100  $\Omega$ . The transmission media may be printed-circuit board traces, backplanes, or cables. The ultimate rate and distance of data transfer is dependent upon the attenuation characteristics of the media, the noise coupling to the environment, and other system characteristics.

The SN65LVDS048 is characterized for operation from -40°C to 85°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

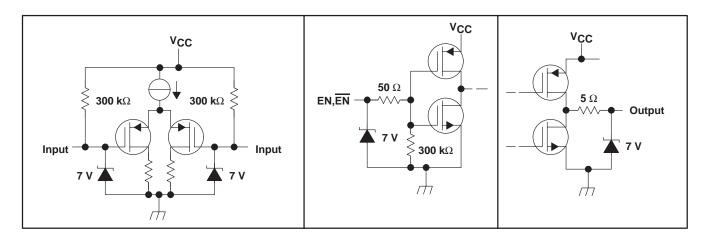


#### **TRUTH TABLE**

DIFFERENTIAL INPUT	ENABLES		OUTPUT
R <sub>IN+</sub> - R <sub>IN-</sub>	EN EN		ROUT
$V_{ID} \ge 100 \text{ mV}$			Н
$V_{ID} \le -100 \text{ mV}$	Н	L or OPEN	L
Open/short or terminated			Н
X	All othe	r conditions	Z

H = high level, L = low level, X = irrelevant, Z = high impedance (off)

## equivalent input and output schematic diagrams



# absolute maximum ratings over operating free-air temperature (unless otherwise noted)†

Supply voltage range (V <sub>CC)</sub>	
Input voltage range, $V_I(R_{IN+}, R_{IN-})$	0.3 V to 4 V
Enable input voltage (EN, EN)	
Output voltage, V <sub>O</sub> (R <sub>OUT</sub> )	
Continuous power dissipation	See Dissipation Rating Table
Storage temperature range	
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values, except differential I/O bus voltages, are with respect to network ground terminal.

#### **DISSIPATION RATING TABLE**

PACKAGE	$T_{\mbox{A}} \le 25^{\circ}\mbox{C}$ POWER RATING	OPERATING FACTOR <sup>‡</sup> ABOVE T <sub>A</sub> = 25°C	T <sub>A</sub> = 85°C POWER RATING
D	950 mW	7.6 mW/°C	494 mW
PW	774 mW	6.2 mW/°C	402 mW

<sup>‡</sup>This is the inverse of the junction-to-ambient thermal resistance when board-mounted and with no air flow.



## recommended operating conditions

	MIN	NOM	MAX	UNIT
Supply voltage, V <sub>CC</sub>	3	3.3	3.6	V
Receiver input voltage	GND		3	V
Common-mode input voltage, V <sub>IC</sub>	$\frac{ V_{ID} }{2}$	2	$2.4 - \frac{ V_{ID} }{2}$	V
			V <sub>CC</sub> – 0.8	
Operating free-air temperature, T <sub>A</sub>	-40	25	85	°C

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Note 2)

PARAMETER		TEST CO	TEST CONDITIONS			MAX	UNIT
V <sub>IT+</sub>	Differential input high threshold voltage	V <sub>CM</sub> = 1.2 V, 0.05 V, 2.35 V				100	\/
V <sub>IT</sub> –	Differential input low threshold voltage	(see Note 3)		-100			mV
V(CMR)	Common mode voltage range	V <sub>ID</sub> = 200 mV pk to pk	(see Note 4)	0.1		2.3	V
	Input current	V <sub>IN</sub> = 2.8 V		-20	±1	20	μΑ
I <sub>IN</sub>		V <sub>IN</sub> = 0 V	VCC = 3.6 V or 0 V	-20	±1	20	μΑ
		V <sub>IN</sub> = 3.6 V	VCC = 0 V	-20	±1	20	μΑ
		$I_{OH} = -0.4 \text{ mA}, V_{ID} =$	200 mV	2.7	3.2		V
VOH Output high volta	Output high voltage	I <sub>OH</sub> = -0.4 mA, input terminated		2.7	3.2		V
		I <sub>OH</sub> = -0.4 mA, input shorted		2.7	3.2		V
VOL	Output low voltage	I <sub>OL</sub> = 2 mA, V <sub>ID</sub> = -200 mV			0.05	0.25	V
los	Output short circuit current	Enabled, V <sub>OUT</sub> = 0 V (see Note 5)			-65	-100	mA
I <sub>O(Z)</sub>	Output 3-state current	Disabled, VOUT = 0 V or VCC		-1		1	μΑ
VIH	Input high voltage			2.0		Vcc	V
V <sub>IL</sub>	Input low voltage			GND		0.8	V
l <sub>l</sub>	Input current (enables)	$V_{IN} = 0 \text{ V or } V_{CC},$ Other input = $V_{CC}$ or GND		-10		10	μΑ
VIK	Input clamp voltage	I <sub>CL</sub> = -18 mA		-1.5	-0.8		V
Icc	No load supply current, receivers enabled	EN = V <sub>CC</sub> , In	puts open		8	15	mA
I <sub>CC(Z)</sub>	No load supply current, receivers disabled	EN = GND, In	puts open		0.6	1.5	mA

<sup>&</sup>lt;sup>†</sup> All typical values are at 25°C and with a 3.3-V supply.

- NOTES: 2. Current into device pin is defined as positive. Current out of the device is defined as negative. All voltages are referenced to ground, unless otherwise specified.
  - 3.  $V_{CC}$  is always higher than  $R_{IN+}$  and  $R_{IN-}$  voltage,  $R_{IN-}$  and  $R_{IN+}$  have a voltage range of  $-0.2\,\text{V}$  to  $V_{CC}-V_{ID}/2$ . To be compliant with ac specifications the common voltage range is 0.1 V to 2.3 V.
  - 4. The VCMR range is reduced for larger  $V_{ID}$ , Example: If  $V_{ID} = 400$  mV, the VCMR is 0.2 V to 2.2 V. The fail-safe condition with inputs shorted is not supported over the common-mode range of 0 V to 2.4 V, but is supported only with inputs shorted and no external common-mode voltage applied. A  $V_{ID}$  up to  $V_{CC}$ -0 V may be applied to the  $R_{IN+}$  and  $R_{IN-}$  inputs with the common-mode voltage set to  $V_{CC}$ /2. Propagation delay and differential pulse skew decrease when  $V_{ID}$  is increased from 200 mV to 400 mV. Skew specifications apply for 200 mV <  $V_{ID}$  < 800 mV over the common-mode range.
  - 5. Output short circuit current (Ios) is specified as magnitude only, minus sign indicates direction only. Only one output should be shorted at a time. Do not exceed maximum junction temperature specification.



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## switching characteristics over recommended operating conditions (unless otherwise noted) (see Notes 6)

	PARAMETER	TEST CONDITIONS	MIN	TYP <sup>†</sup>	MAX	UNIT
<sup>t</sup> PHL	Differential propagation delay, high-to-low		1.9	2.7	3.7	ns
<sup>t</sup> PLH	Differential propagation delay, low-to-high	]	1.9	2.9	3.7	ns
tSK(p)	Differential pulse skew (tpHLD - tpLHD) (see Note 7)			200	450	ps
tSK(o)	Differential channel-to-channel skew; same device (see Note 8)	C <sub>L</sub> = 15 pF		50	500	ps
tSK(pp)	Differential part-to-part skew (see Note 9)	V <sub>ID</sub> = 200 mV (see Figure 1 and 2)			1	ns
tSK(lim)	Differential part-to-part skew (see Note10)				1.5	ns
t <sub>r</sub>	Rise time	]		0.5	1	ns
t <sub>f</sub>	Fall time			0.5	1	ns
<sup>t</sup> PHZ	Disable time high to Z			8	9	ns
<sup>t</sup> PLZ	Disable time low to Z	$R_L = 2 K \Omega$ $C_I = 15 pF$		6	8	ns
<sup>t</sup> PZH	Enable time Z to high	(see Figure 3 and 4)		8	10	ns
tPZL	Enable time Z to low	1		7	8	ns
f(MAX)	Maximum operating frequency (see Note 11)	All channels switching	200	250		MHz

<sup>†</sup> All typical values are at 25°C and with a 3.3-V supply.

- NOTES: 6. Generator waveform for all tests unless otherwise specified: f = 1 MHz,  $Z_O = 50 \Omega$ , tr and tf  $(0\% 100\%) \le 3 \text{ ns}$  for  $R_{IN}$ .
  - 7. tsk(p)|tpLH tpHL| is the magnitude difference in differential propagation delay time between the positive going edge and the negative going edge of the same channel.
  - 8.  $t_{SK(0)}$  is the differential channel-to-channel skew of any event on the same device.
  - 9.  $t_{SK(pp)}$  is the differential part-to-part skew, and is defined as the difference between the minimum and the maximum specified differential propagation delays. This specification applies to devices at the same VCC and within 5°C of each other within the operating temperature range.
  - 10. t<sub>sk(lim)</sub> part-to-part skew, is the differential channel-to-channel skew of any event between devices. This specification applies to devices over recommended operating temperature and voltage ranges, and across process distribution. t<sub>Sk(lim)</sub> is defined as |Min - Maxl differential propagation delay.
  - 11.  $f_{\text{(MAX)}}$  generator input conditions:  $t_{\text{f}} = t_{\text{f}} < 1 \text{ ns}$  (0% to 100%), 50% duty cycle, 0 V to 3 V. Output criteria: duty cycle = 45% to 55%, VOD > 250 mV, all channels switching



## PARAMETER MEASUREMENT INFORMATION

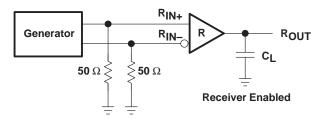


Figure 1. Receiver Propagation Delay and Transition Time Test Circuit

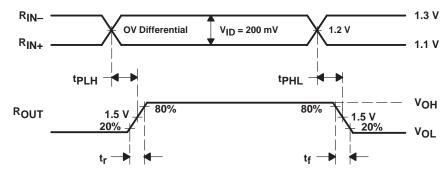
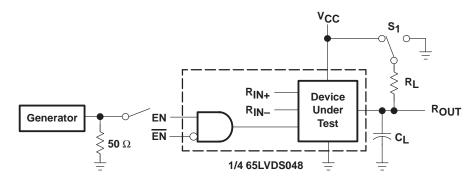


Figure 2. Receiver Propagation Delay and Transition Time Waveforms

## PARAMETER MEASUREMENT INFORMATION



 $C_L$  Includes Load and Test Jig Capacitance.  $S_1 = V_{CC}$  for  $t_{PZL}$  and  $t_{PLZ}$  Measurements.

S<sub>1</sub> = GND for tpzH and tpHz Measurements.

Figure 3. Receiver 3-State Delay Test Circuit

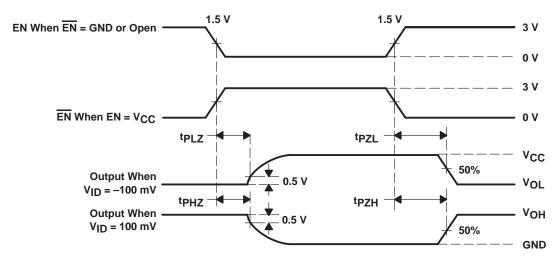
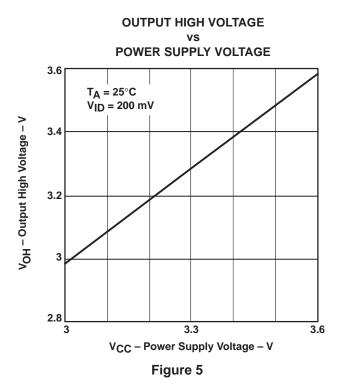
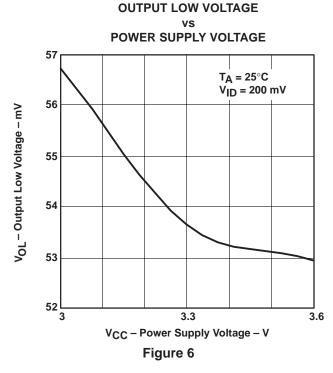
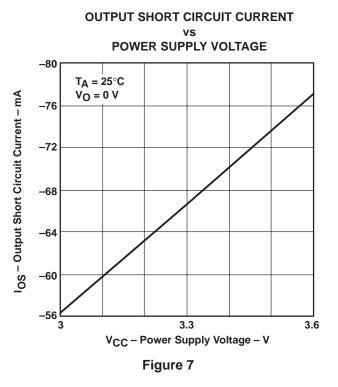


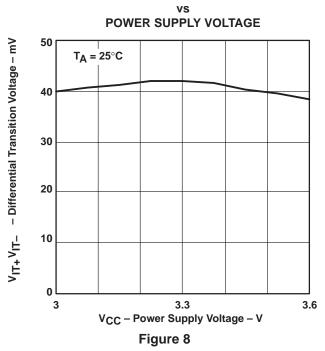
Figure 4. Receiver 3-State Delay Waveforms

#### TYPICAL CHARACTERISTICS



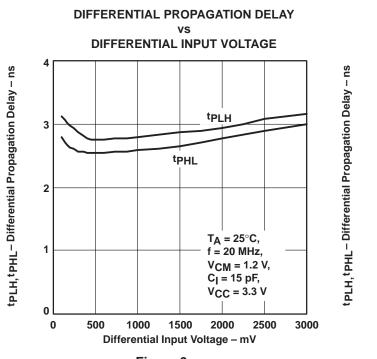






**DIFFERENTIAL TRANSITION VOLTAGE** 

## **TYPICAL CHARACTERISTICS**



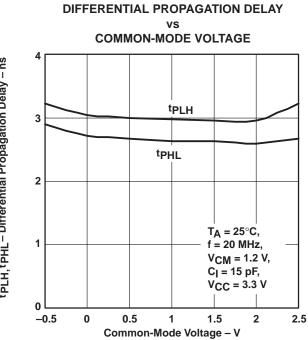


Figure 10

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#### **APPLICATION INFORMATION**

#### fail safe

One of the most common problems with differential signaling applications is how the system responds when no differential voltage is present on the signal pair. The LVDS receiver is like most differential line receivers, in that its output logic state can be indeterminate when the differential input voltage is between –100 mV and 100 mV and within its recommended input common-mode voltage range. TI's LVDS receiver is different in how it handles the open-input circuit situation, however.

Open-circuit means that there is little or no input current to the receiver from the data line itself. This could be when the driver is in a high-impedance state or the cable is disconnected. When this occurs, the LVDS receiver will pull each line of the signal pair to near  $V_{CC}$  through 300-k $\Omega$  resistors as shown in Figure 10. The fail-safe feature uses an AND gate with input voltage thresholds at about 2.3 V to detect this condition and force the output to a high-level regardless of the differential input voltage.

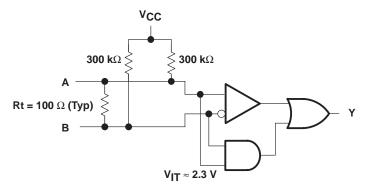


Figure 11. Open-Circuit Fail Safe of the LVDS Receiver

It is only under these conditions that the output of the receiver will be valid with less than a 100 mV differential input voltage magnitude. The presence of the termination resistor, Rt, does not affect the fail-safe function as long as it is connected as shown in the figure. Other termination circuits may allow a dc current to ground that could defeat the pullup currents from the receiver and the fail-safe feature.

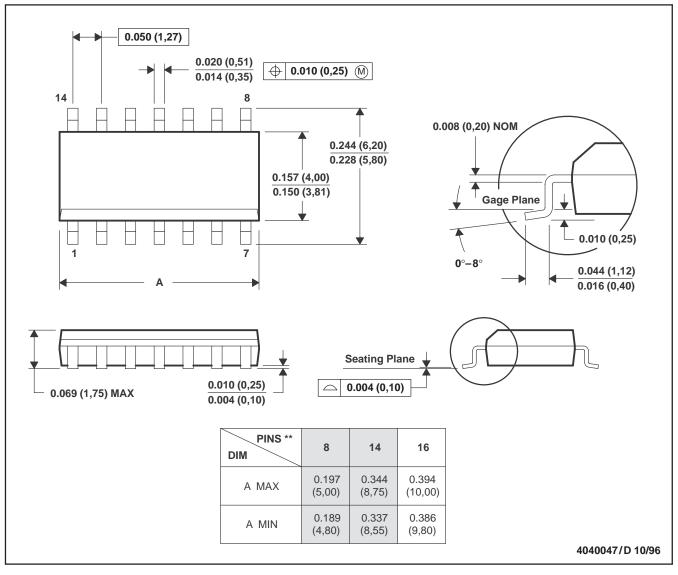
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## **MECHANICAL DATA**

## D (R-PDSO-G\*\*)

## 14 PINS SHOWN

## PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0.006 (0,15).

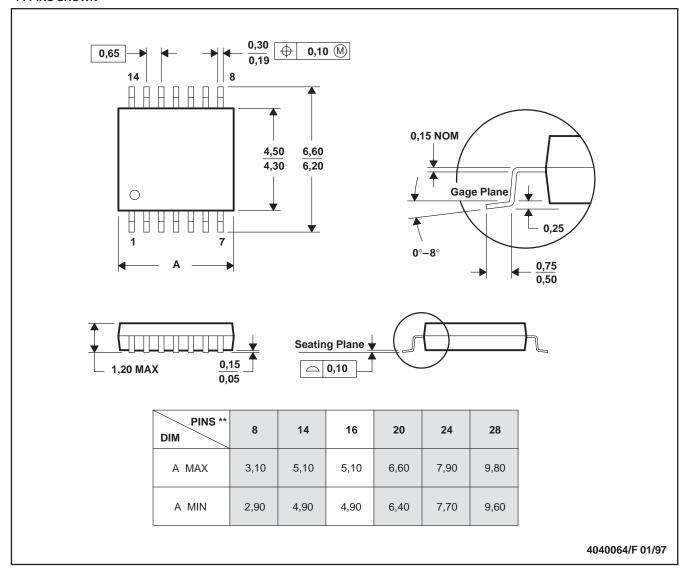
D. Falls within JEDEC MS-012

## **MECHANICAL DATA**

## PW (R-PDSO-G\*\*)

#### 14 PINS SHOWN

## PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153





ti.com 30-Mar-2005

#### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN65LVDS048D	OBSOLETE	SOIC	D	16	TBD	Call TI	Call TI
SN65LVDS048DR	OBSOLETE	SOIC	D	16	TBD	Call TI	Call TI
SN65LVDS048PW	OBSOLETE	TSSOP	PW	16	TBD	Call TI	Call TI
SN65LVDS048PWR	OBSOLETE	TSSOP	PW	16	TBD	Call TI	Call TI

<sup>&</sup>lt;sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

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a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

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TBD: The Pb-Free/Green conversion plan has not been defined.

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(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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Mailing Address: Texas Instruments

Post Office Box 655303 Dallas, Texas 75265

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